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APPLICATION NO.	TION NO. FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/387,477	09/01/	/1999	Manabu Tomita	TIJ-26105 2630		
23494	7590	04/05/2002	·			
TEXAS INSTRUMENTS INCORPORATED				EXAMINER		
P O BOX 6 DALLAS, 7	55474, M/S 399 FX 75265	99		GUERRERO, MARIA F		
				ART UNIT	PAPER NUMBER	
				2822		
				DATE MAIL ED. 04/05/2002	•	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	r
	09/387,477	TOMITA ET AL.	
Offic Action Summary	Examiner	Art Unit	
	Maria Guerrero	2822	
- The MAILING DATE of this communication app Peri df r Reply	ars on the c ver sheet v	vith the correspondence addres	SS
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.131 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period with the set or extended period for reply will, by statute, and reply received by the Office later than three months after the mailing the earned patent term adjustment. See 37 CFR 1.704(b). Status	6(a). In no event, however, may a within the statutory minimum of thi ill apply and will expire SIX (6) MO cause the application to become A	reply be timely filed irty (30) days will be considered timely. NTHS from the mailing date of this commu	nication.
1)⊠ Responsive to communication(s) filed on <u>18 Ja</u>	anuani 2002		
·_ · · · · · · · · · · · · · · · · · ·	s action is non-final.		
, <u> </u>			
3) Since this application is in condition for allowar closed in accordance with the practice under E	Ex parte Quayle, 1935 C	atters, prosecution as to the m .D. 11, 453 O.G. 213.	erits is
Disposition of Claims	•	,	
4)⊠ Claim(s) <u>1 and 3-7</u> is/are pending in the applica	ation.		
4a) Of the above claim(s) is/are withdraw	n from consideration.		
5) Claim(s) is/are allowed.			
6)⊠ Claim(s) <u>1 and 3-7</u> is/are rejected.			
7) Claim(s) is/are objected to.			
8) Claim(s) are subject to restriction and/or	election requirement.		
Application Papers			•
9)☐ The specification is objected to by the Examiner.			
10) The drawing(s) filed on is/are: a) □ accept	ed or b) objected to by	the Examiner.	
Applicant may not request that any objection to the	drawing(s) be held in abey	rance. See 37 CFR 1.85(a).	
11) The proposed drawing correction filed on	is: a)□ approved b)□ o	disapproved by the Examiner.	
If approved, corrected drawings are required in repl	y to this Office action.		
12)☐ The oath or declaration is objected to by the Exa	miner.		
Pri rity under 35 U.S.C. §§ 119 and 120			
13) Acknowledgment is made of a claim for foreign	priority under 35 U.S.C.	§ 119(a)-(d) or (f).	
a)⊠ All b)☐ Some * c)☐ None of:			
1. Certified copies of the priority documents	have been received.		
2. Certified copies of the priority documents	have been received in A	Application No	
 3. Copies of the certified copies of the priorit application from the International Bure * See the attached detailed Office action for a list of 	ty documents have been eau (PCT Rule 17.2(a)).	received in this National Stag	e
	•		
14) Acknowledgment is made of a claim for domestic			iication).
 a) ☐ The translation of the foreign language prov. 15) ☐ Acknowledgment is made of a claim for domestic 			
Attachment(s)			
)	5) Notice of	Summary (PTO-413) Paper No(s) Informal Patent Application (PTO-152	

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DETAILED ACTION

1. This Office Action is in response the Amendment filed January 18, 2002.

Claims 2, 8-9 are canceled.

Claims 1, 3-7 are pending.

Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

2. Claims 1, 3-7 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. The specification does not provide support for the new limitation "the fluorocarbon gas having the lower ratio of carbon atoms to fluorine atoms forming at least one half of the mixed gas".

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Claim Rejecti ns - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.
- 3. Claims 1, 3-4 are rejected under 35 U.S.C. 102(b) as being anticipated by Arleo et al. (U.S. 5,176,790).

Arleo et al. teaches providing a semiconductor substrate having an insulating layer, etching the insulating layer using a mixed of fluorocarbon gases that have different ratios of carbon atoms to fluorine atoms (fig. 1-3, col. 1, lines 20-30, col. 3, lines 20-25, 40-50, col. 4, lines 38-55). Arleo et al. discloses the mixed of fluorocarbon gases comprises a first amount of first fluorocarbon gas with a large C/F ratio, mixed with a second amount of a second fluorocarbon gas with a small C/F ratio, the amount of the second fluorocarbon gas being less than the amount of the first fluorocarbon gas (col. 3, 20-52, col. 4, lines 40-50, col. 6, lines 1-5). In addition, Arleo et al. teaches using C₄F₈ as first fluorocarbon gas and at least one of CHF₃, CF₄ as a second fluorocarbon gas (col. 3, lines 20-25, 40-52, col. 8, lines 9-17, col. 11, lines 34-45). Arleo et al. discloses the insulating layer being plasma etched, the semiconductor substrate having a lower conducting layer (fig. 1-2, col. 3, lines 5-20, col. 11, lines 5-10).

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4. Claims 1, 3 are rejected under 35 U.S.C. 102(e) as being anticipated by Liu et al. (U.S. 5,906,948).

Liu et al. teaches providing a semiconductor substrate having an insulating layer, etching the insulating layer using a mixed of fluorocarbon gases that have different ratios of carbon atoms to fluorine atoms (Abstract). Liu et al. discloses the mixed of fluorocarbon gases comprises a first amount of first fluorocarbon gas with a large C/F ratio, mixed with a second amount of a second fluorocarbon gas with a small C/F ratio, the amount of the second fluorocarbon gas being less than the amount of the first fluorocarbon gas (col. 3, lines 20-30). Liu et al. teaches using C₄F₈ as first fluorocarbon gas and CHF₃ as a second fluorocarbon gas (Abstract, col. 3, lines 20-30).

5. Claim 1 is rejected under 35 U.S.C. 102(e) as being anticipated by Tang et al. (U.S. 6,211,092).

Tang et al. teaches providing a semiconductor substrate having an insulating layer, etching the insulating layer using a mixed of fluorocarbon gases that have different ratios of carbon atoms to fluorine atoms (Abstract).

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Claim R j ctions - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 6. Claims 3-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tang et al. (U.S. 6,211,092) in view of Miyazaki et al. (U.S. 5,804,878).

Regarding claims 3-7, Tang et al. teaches a plasma-etching process using fluorocarbon gases such as, C₄F₈, CHF₃, and CH₂F₂ (Abstract, col. 6, lines 5-15). Tang et al. discloses using silicon oxide using TEOS and spin-on glass layers (col. 2, lines 10-12, col. 14, lines 40-50). Tang et al. teaches as conventional in the art, advanced integrated circuits contain multiple wiring layers separated from the silicon substrate and from each other by dielectric layers; several layers of metallization with intervening interlevel dielectric layers are required; and contact or via holes are filled with a conductor typically aluminum col. 1, lines 35-55).

Tang et al. fails to show the lower conducting layer having a titanium nitride layer, a layer of aluminum, a titanium layer and a titanium nitride layer stacked in that order. However, Miyazaki et al. shows the use of these materials as conventional in the art (Abstract, fig. 1 (D), col. 2, lines 1-12, 30-40, col. 4, lines 45-60).

Therefore, it would have been obvious to a person of ordinary skill in the art at the time of the invention to include Miyazaki et al.'s teachings in Tang et al.'s process.

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The modification would provide a process that can be applied to a dual damascene structure and to other multi-layer dielectric structures.

In addition, the amount of etching gas is considered to be obvious, since this is a variable of art that is subject to routine experimentation and discovery of an optimum value for a known process is obvious. In re Aller, 105 USPQ 233 (CCPA 1955). In re Geisler, CA FC, No. 96-1362, July 7, 1997.

Response to Arguments

7. Applicant's arguments with respect to claims 1, 3-7 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

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the advisory action. In no event, however, will the statutory period for reply expire later

than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Maria Guerrero whose telephone number is 703-305-

0162.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Carl Whitehead Jr. can be reached on 703-308-4940. The fax phone

numbers for the organization where this application or proceeding is assigned are 703-

308-7722 for regular communications and 703-308-7382 for After Final

communications.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is 703-308-

0956.

April 4, 2002

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